

Amendments to the Claims

This listing of claims will replace all prior listings of claims in the application.

Listing of Claims

1. (Canceled)
2. (Canceled)
3. (Previously Presented) The connecting material as claimed in claim 8, wherein it comprises 2-40%, based on the volume of the adhesive component, of the electro-conductive particles.
4. (Canceled)
5. (Canceled)
6. (Previously Presented) The COG assembly as claimed in claim 9, wherein the connecting material comprises 2-40%, based on the volume of the adhesive component, of the electroconductive particles.
7. (Previously Presented) The COG assembly as claimed in claim 9, wherein the COG assembly is a liquid crystal display.
8. (Currently Amended) A connecting material for bonding and connecting a semiconductor chip with a substrate glass board and forming a COG assembly in which electrodes provided on the semiconductor chip are held in direct connection with corresponding electrodes provided on the substrate glass board, said connecting material having a

tensile elongation percentage at 25°C of at least 5%, after being cured, and comprising:

an adhesive component comprising

10-94% by weight of an epoxy resin,

~~0-50~~5-30% by weight of a thermoplastic polymeric substance and

6-90 wt.% of a microparticulate elastomer product selected from the group consisting of natural rubber, isoprene rubber, butadiene rubber, styrene/butadiene rubber, chloroprene rubber and acrylonitrile/butadiene rubber having an average particle size of 30-300 nm and electroconductive particles.

9. (Currently Amended) A COG assembly comprising a semiconductor chip having electrodes provided thereon and a substrate glass board having electrodes provided thereon corresponding to the electrodes provided on the semiconductor chip, the electrodes provided on the semiconductor chip being held in direct connection with the corresponding electrodes provided on the substrate glass board by a connecting material, the connecting material having a tensile elongation percentage of at least 5% at 25°C, after being cured, and comprising an adhesive component comprising 10-94% by weight of an epoxy resin, ~~0-50~~5-30% by weight of a thermoplastic polymeric substance, 6-90 wt.% of a microparticulate elastomer product selected from the group consisting of natural rubber, isoprene rubber, butadiene rubber, styrene/butadiene rubber, chloroprene rubber and acrylonitrile/butadiene rubber having an average particle size of 30-300 nm and electroconductive particles.

10. (Previously Presented) The connecting material of Claim 8, wherein the microparticulate elastomer has an average particle size of 50-200 nm.

11. (Previously Presented) The COG assembly of Claim 9, wherein the microparticulate elastomer has an average particle size of 50-200 nm.

12. (Previously Presented) The connecting material of Claim 8, wherein the electroconductive particles have an average particle size of from 1-20 μm .

13. (Previously Presented) The COG assembly of Claim 9, wherein the electroconductive particles have an average particle size of from 1-20 μm .

14. (Canceled)

15. (Canceled)

16. (Canceled)

17. (Canceled)

18. (Previously Presented) The connecting material of Claim 8, wherein the cured connecting material has an elastic modulus of from 0.9-3 GPa at 30°C and a Tg of from 110-160°C.

19. (Previously Presented) The COG assembly of Claim 9, wherein the cured connecting material has an elastic modulus of from 0.9-3 GPa at 30°C and a Tg of from 110-160°C.

20. (Canceled)

21. (Canceled)